

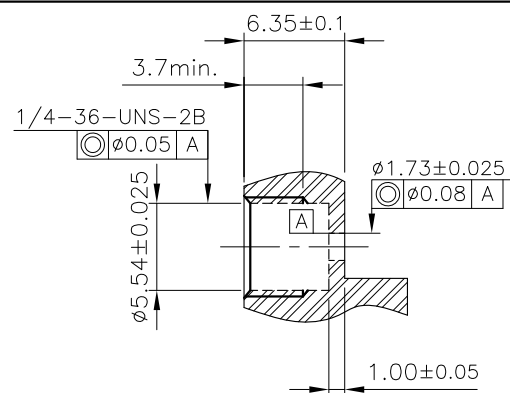
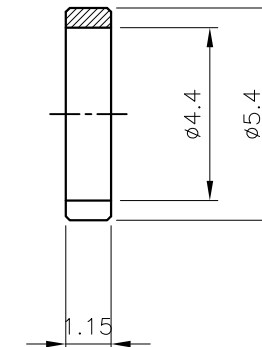
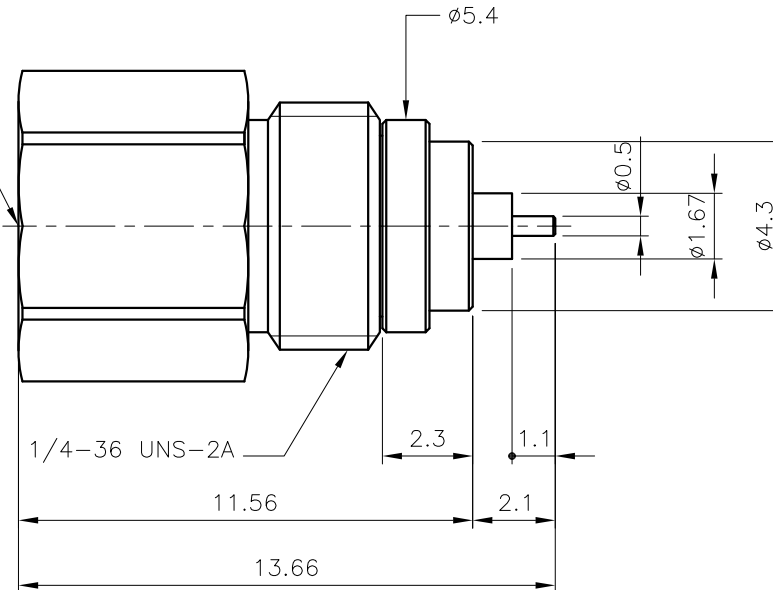
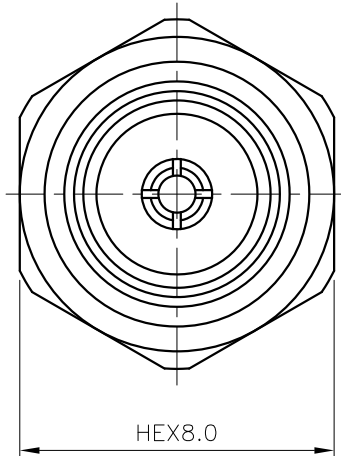
Note.

1. This product is manufactured for military use according to MIL-SPEC

REVISION

REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.H.KIM		2024. 01.29.

BMA JACK



PANEL PIERCING SCALE 2:1

7	METALLIC GASKET	1	AL6061	Silver Plate (5μm)	DSR01210-5/1
6	PIN COVER	1	MBsBD C36048D-F	Gold Plate	DIB00026-5/1
5	PLATE SPRING	1	BeCu C17300	Gold Plate	DPS00002-5/1
4	INSULATOR	1	TEFLON		DIN03385-N/1
3	CONTACT	1	BeCu C17300	Gold Plate (1.3μm)	DCT04416-5/1
2	BODY (B)	1	MBsBD C36048D-F	Gold Plate	DBD04927-5/2
1	BODY (A)	1	SUS303	Passivated	DBD04929-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2024. 01. 29.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	Angle ±1°	APPROVED BY				
MATERIAL _____	CHECKED BY			TITLE BMA50 SOLDER END JB(R/N)		
	DRAWN BY S.H.KIM					
FINISH _____	SCALE 5/1	UNIT mm		A4	DWG NO. CN04130-7/1	
					REVISION I R	SHEET 1 of 1